

Specification of Thermoelectric Module

TES1-03850OD24ID9.8

Description

The 38 couples round shape with center hole, 24 mm (OD) × 9.8 (ID) mm size single module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C/200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

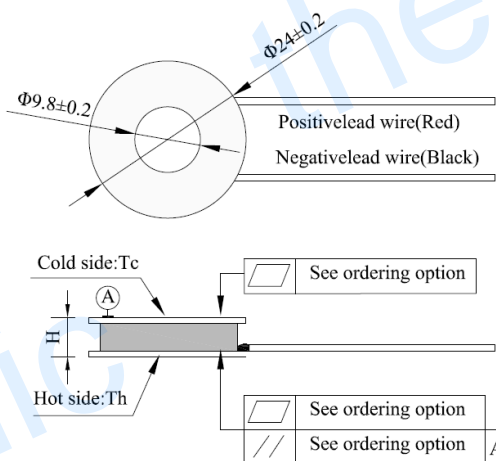
Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

Performance Specification Sheet

Th(°C)	27	50	Hot side temperature at environment: dry air, N ₂
DT _{max} (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U _{max} (Voltage)	4.7	5.2	Voltage applied to the module at DT _{max}
I _{max} (amps)	5.8	5.8	DC current through the modules at DT _{max}
Q _{Cmax} (Watts)	17.1	19.2	Cooling capacity at cold side of the module under DT=0 °C
AC resistance(ohms)	0.63	0.68	The module resistance is tested under AC
Tolerance (%)	± 10		For thermal and electricity parameters

Geometric Characteristics Dimensions in millimeters



Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0:3.1 ± 0.1	0:0.05/0.05	50±1/Specify
TF	1:3.1 ± 0.05	1:0.025/0.025	50±1/Specify
TF	2:3.1 ± 0.025	2:0.015/0.015	50±1/Specify

Eg. TF01: Thickness 3.1 ± 0.1 (mm) and Flatness 0.025/0.25 (mm)

Manufacturing Options

A. Solder:

1. T100: BiSn (T_{melt}=138°C)
2. T200: CuSn (T_{melt} = 227 °C)

B. Sealant:

1. NS: No sealing (Standard)
2. SS: Silicone sealant
3. EPS: Epoxy sealant
4. Customer specify sealing

other than above

C. Ceramics:

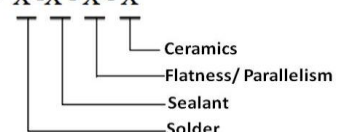
1. Alumina (Al₂O₃, white 96%)
2. Aluminum Nitride (AlN)

D. Ceramics Surface Options:

1. Blank ceramics (not metallized)
2. Metallized (Au plating)

Naming for the Module

TES1- 03850- X-X - X - X



TES1- 03850-T100 -NS -TF01 -AIO

T100: BiSn (T_{melt}=138°C)

NS: No sealing

AIO: Alumina, white 96%

TF01: Thickness ± 0.1 (mm) and Flatness/ Parallelism 0.025/0.025 (mm)

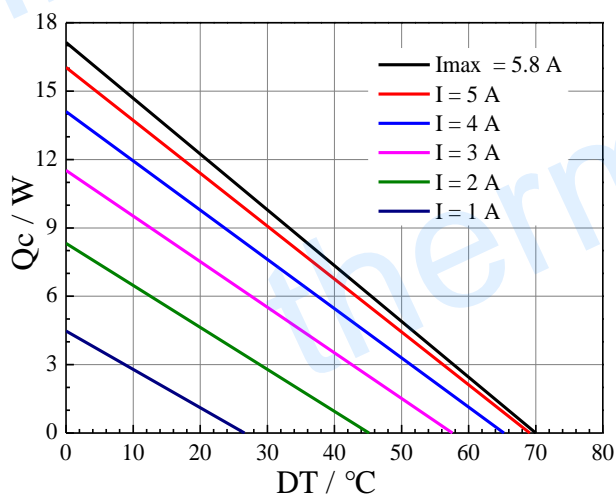
Creative technology with fine manufacturing processes provides you the reliable and quality products

Tel: +86-791-88198288 Fax: +86-791-88198308 Email: sales@thermonamic.com.cn Web Site: www.thermonamic.com.cn

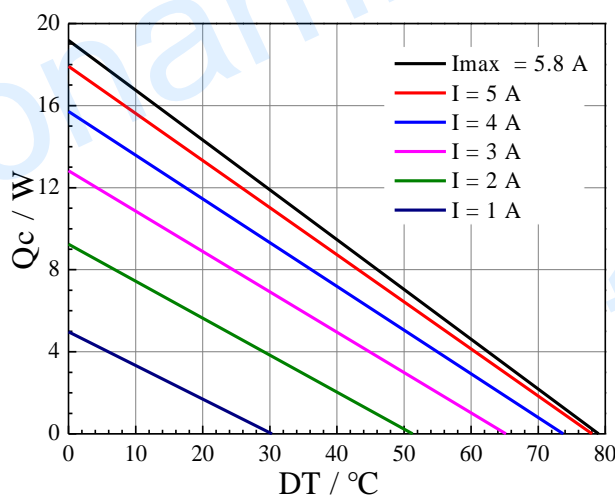
Specification of Thermoelectric Module

TES1-03850OD24ID9.8

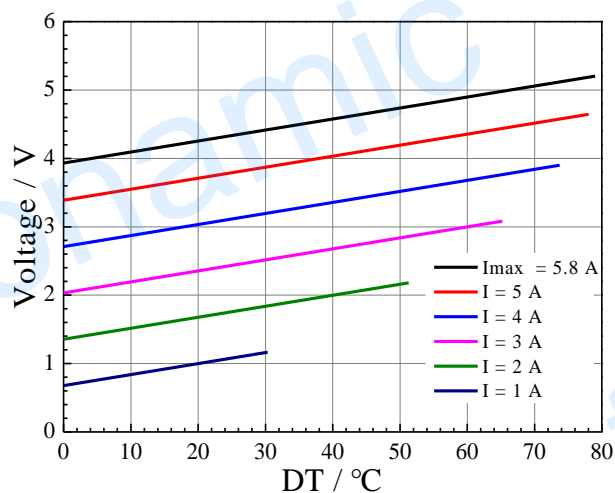
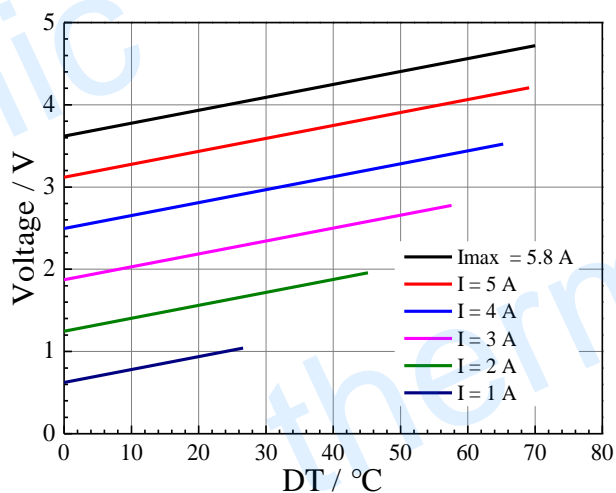
Performance Curves at $T_h=27\text{ }^\circ\text{C}$



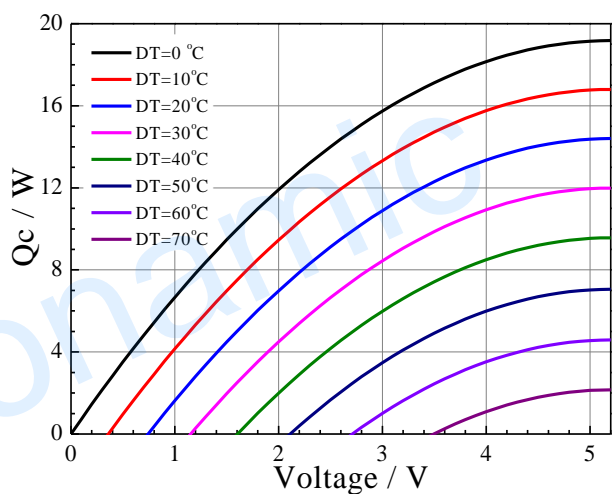
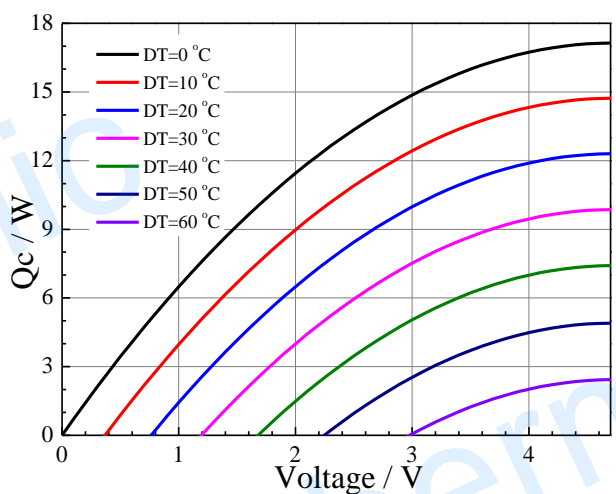
Performance Curves at $T_h=50\text{ }^\circ\text{C}$



Standard Performance Graph $Q_c = f(DT)$



Standard Performance Graph $V = f(DT)$

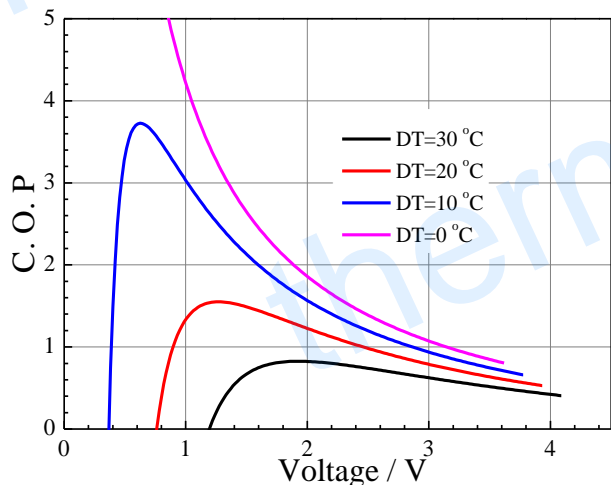


Standard Performance Graph $Q_c = f(V)$

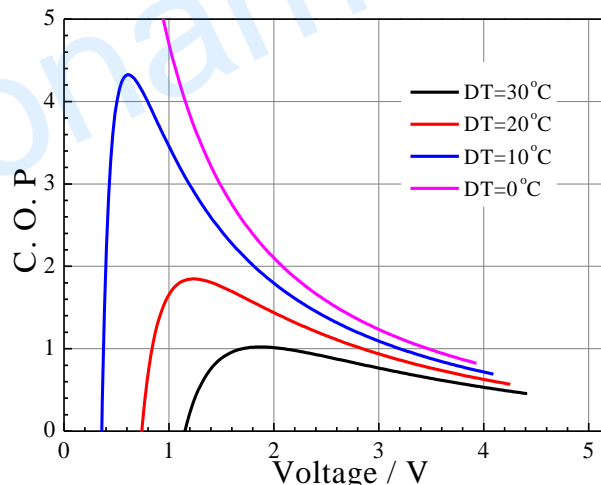
Specification of Thermoelectric Module

TES1-03850D24ID9.8

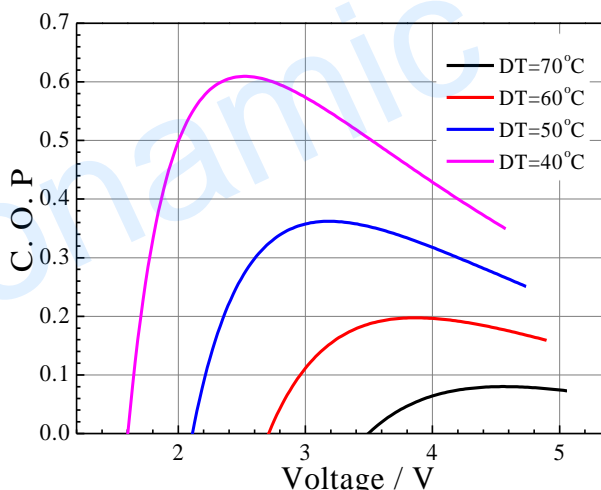
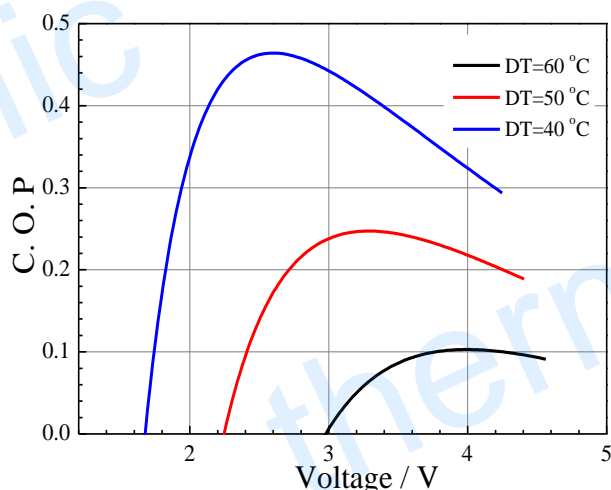
Performance Curves at Th=27 °C



Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Q_c /Input power ($V \times I$).

Operation Cautions

- Cold side of the module stucked on the object being cooled
- Hot side of the module mounted on a heat radiator
- Operation below I_{max} or V_{max}
- Work under DC

Note: All specifications subject to change without notice.